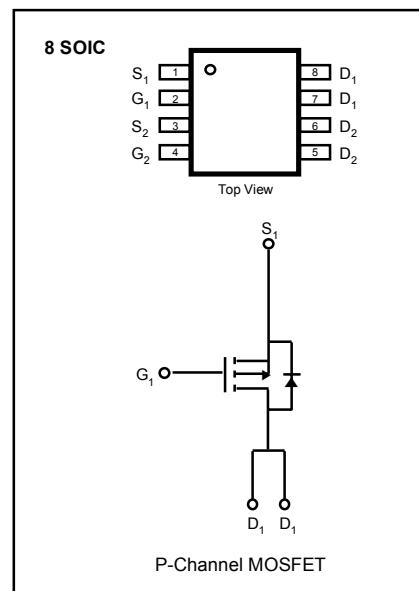


## FEATURES

- Lower  $R_{DS(ON)}$
- Improved Inductive Ruggedness
- Fast Switching Times
- Low Input Capacitance
- Extended Safe Operating Area
- Improved High Temperature Reliability

## Product Summary

Part Number	BVdss	Rds(on)	I <sub>D</sub>
SSD2005	-25V	0.25Ω	-2.3A



## Absolute Maximum Ratings

Symbol	Characteristic	Value	Units
V <sub>DSS</sub>	Drain-to-Source Voltage	-25	V
I <sub>D</sub>	Continuous Drain Current T <sub>A</sub> =25°C	-2.3	A
	Continuous Drain Current T <sub>A</sub> =70°C	-1.9	
I <sub>DM</sub>	Drain Current-Pulsed ①	-9.2	A
V <sub>GS</sub>	Gate-to-Source Voltage	±20	V
P <sub>D</sub>	Total Power Dissipation (T <sub>A</sub> =25°C)	2.0	W
	(T <sub>A</sub> =70°C)	1.3	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Junction Storage Temperature Range	-55 to +150	°C

## Thermal Resistance

Symbol	Characteristic	Typ.	Max.	Units
R <sub>θJA</sub>	Junction-to-Ambient	--	62.5	°C/W



**Electrical Characteristics** ( $T_C=25^\circ\text{C}$  unless otherwise specified)

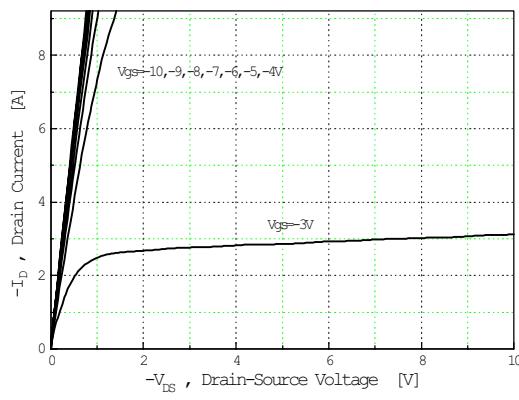
Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	-25	--	--	V	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=-250\mu\text{A}$
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	-1.0	--	-3.0	V	$\text{V}_{\text{DS}}= -5\text{V}, \text{I}_D=-250\mu\text{A}$
$\text{I}_{\text{GSS}}$	Gate-Source Leakage , Forward	--	--	-100	nA	$\text{V}_{\text{GS}}=-20\text{V}$
	Gate-Source Leakage , Reverse	--	--	100	nA	$\text{V}_{\text{GS}}=20\text{V}$
$\text{I}_{\text{DSS}}$	Drain-to-Source Leakage Current	--	--	-2.0	$\mu\text{A}$	$\text{V}_{\text{DS}}=-20\text{V}$
		--	--	-25		$\text{V}_{\text{DS}}=-20\text{V}, \text{T}_C=55^\circ\text{C}$
$\text{I}_{\text{DON}}$	On-State Drain-Source Current	-10	--	--	A	$\text{V}_{\text{DS}}=-5\text{V}, \text{V}_{\text{GS}}=-10\text{V}$
$\text{R}_{\text{DS(on)}}$	Static Drain-Source On-State Resistance <sup>(2)</sup>	--	0.08	0.25	$\Omega$	$\text{V}_{\text{GS}}=-10\text{V}, \text{I}_D=-1.0\text{A}$
		--	0.11	0.40		$\text{V}_{\text{GS}}=-4.5\text{V}, \text{I}_D=-0.5\text{A}$
$\text{g}_{\text{fs}}$	Forward Transconductance <sup>(2)</sup>	--	5.0	--	$\text{S}$	$\text{V}_{\text{DS}}=-15\text{V}, \text{I}_D=-1.0\text{A}$
$t_{\text{d(on)}}$	Turn-On Delay Time	--	17	40	ns	$\text{V}_{\text{DD}}=-25\text{V}, \text{I}_D=-1.0\text{A}, \text{R}_0=6.0\Omega,$ <sup>(2)(3)</sup>
$t_r$	Rise Time	--	17	40		
$t_{\text{d(off)}}$	Turn-Off Delay Time	--	33	90		
$t_f$	Fall Time	--	19	50		
$\text{Q}_g$	Total Gate Charge	--	17	25	nC	$\text{V}_{\text{DS}}=-12.5\text{V}, \text{V}_{\text{GS}}=-10\text{V}, \text{I}_D=-2.3\text{A}$ <sup>(2)(3)</sup>
$\text{Q}_{\text{gs}}$	Gate-Source Charge	--	3.3	--		
$\text{Q}_{\text{gd}}$	Gate-Drain( " Miller " ) Charge	--	3.6	--		

**Source-Drain Diode Ratings and Characteristics**

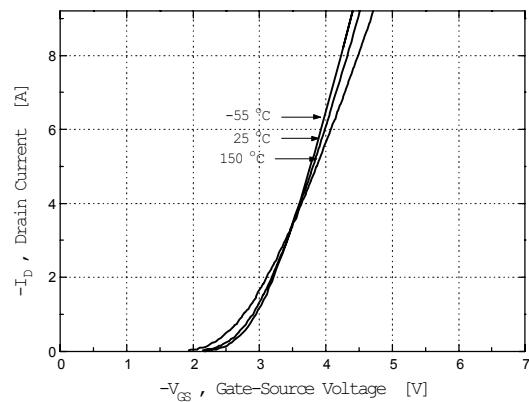
Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
$\text{I}_s$	Continuous Source Current (Body Diode)	--	--	-1.25	A	Modified MOSFET Symbol Showing the Integral Reverse P-N Junction Rectifier 
$\text{V}_{\text{SD}}$	Diode Forward Voltage <sup>(2)</sup>	--	--	-1.6	V	$\text{T}_A=25^\circ\text{C}, \text{I}_s=-1.25\text{A}, \text{V}_{\text{GS}}=0\text{V}$
$t_{\text{rr}}$	Reverse Recovery Time <sup>(2)</sup>	--	--	150	ns	$\text{T}_A=25^\circ\text{C}, \text{I}_F=-1.25\text{A}, \text{di}_F/\text{dt}=100\text{A}/\mu\text{s}$

**Notes :**<sup>(1)</sup> Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature<sup>(2)</sup> Pulse Test : Pulse Width = 250 $\mu\text{s}$ , Duty Cycle  $\leq 2\%$ <sup>(3)</sup> Essentially Independent of Operating Temperature

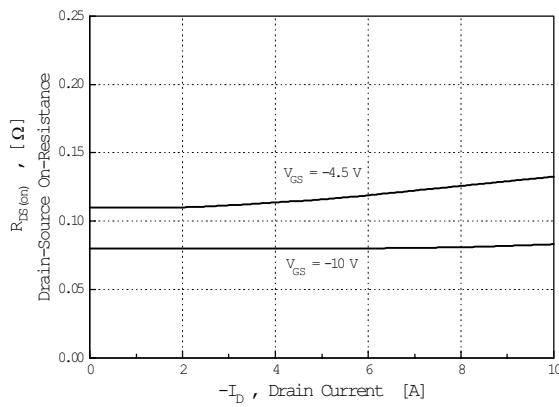
**Fig 1. Output Characteristics**



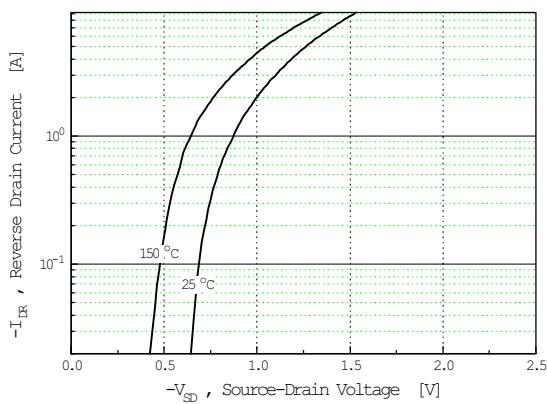
**Fig 2. Transfer Characteristics**



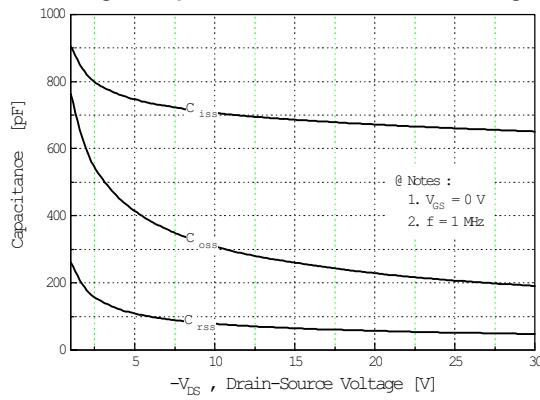
**Fig 3. On-Resistance vs. Drain Current**



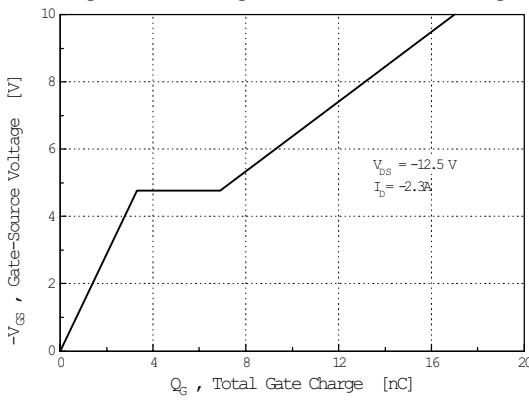
**Fig 4. Source-Drain Forward Voltage**



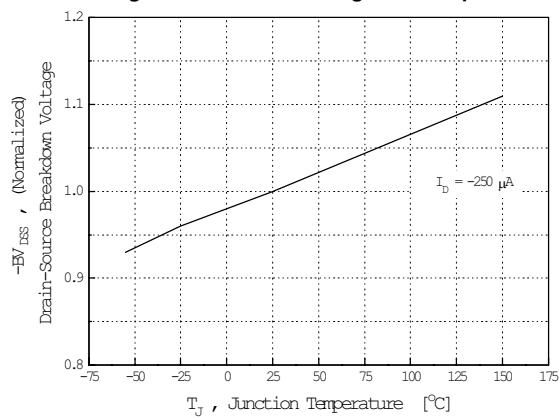
**Fig 5. Capacitance vs. Drain-Source Voltage**



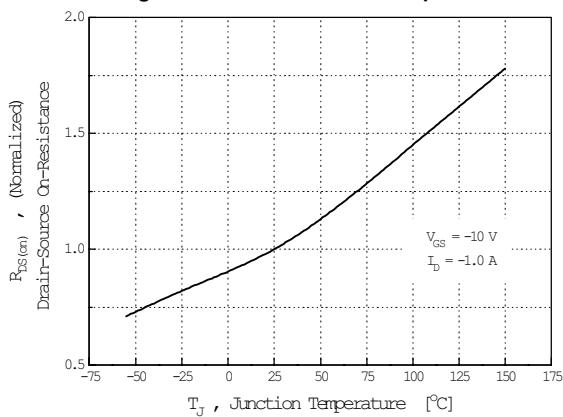
**Fig 6. Gate Charge vs. Gate-Source Voltage**



**Fig 7. Breakdown Voltage vs. Temperature**



**Fig 8. On-Resistance vs. Temperature**



**Fig 9. Normalized Effective Transient Thermal Impedance, Junction-to-Ambient**

